LISTING OF THE CLAIMS

The present listing of claims replaces all prior versions.

Claims 1 –7. (Cancelled)

Claim 8. (Currently amended) Dip soldering apparatus applying solder to component leads extending downwardly from a printed circuit board, said apparatus comprising:

a reservoir for molten solder;

an assembly including an elongate plate provided in the reservoir and ~~positioned at~~ movable relative to a surface of the molten solder by means of spring-biased arms which support and move said plate; and

a holder supporting said printed circuit board, said holder and said reservoir defining one of a first and a second condition, wherein, said first condition said printed circuit board is positioned away from said reservoir and in said second condition said printed circuit board is positioned above said reservoir with said component leads extending at least partially into said molten solder;

wherein said plate has an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned in said second condition to fit between adjacent component leads so that said adjacent component are disposed on each side of the plate edge respectively and the plate ~~surface~~ surfaces being of a material which is wetted by the molten solder.

2

Claim 9. (Currently Amended) Dip soldering apparatus applying solder to the leads of an electronic component, said apparatus comprising:

a nozzle having an outlet through which solder is flowed in use; and

a component holder supporting said component, said holder being movable between a raised condition in which said component is remote from said nozzle and a lowered condition in which leads to be soldered are dipped into the solder surface at the nozzle outlet;

wherein ~~the nozzle includes a~~ member provided at the nozzle outlet and has ~~having a~~ surface which is wetted by the ~~sold or~~ solder, the surface being positioned so as to be straddled by two adjacent leads;

wherein the member is movable relative to the solder surface and the nozzle such that it rises upwardly ~~positioned~~ so as to project through the solder surface as said component holder is moved toward said raised condition and as the leads are withdrawn from the solder.

.

Claims 10 –18. (Cancelled)

Claim 19. (Previously Presented) The apparatus of claim 9, wherein the member has a honeycomb structure.

Claims 20 –24. (Cancelled).

3

Claim 25. (Currently Amended) Dip soldering apparatus comprising a holder supporting a component with leads, a nozzle having an outlet through which solder is flowed in use, leads of the component to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a nozzle member assembly provided at the nozzle outlet, said nozzle member assembly ~~and~~ having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads and wherein the nozzle member assembly includes arms, said arms are spring biased or are electrically controlled so as to support and move said member assembly relative to the surface of the solder~~to be soldered~~;

said apparatus further including means for lowering the solder surface in order to effect withdrawal of the leads from the solder

.

Claim 26. (currently amended) The apparatus of claim 25, wherein said nozzle assembly member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 27. (Cancelled).

Claim 28. (currently amended) The apparatus of claim 25, wherein said nozzle member assembly is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

4

Claim 29. (Currently Amended) Dip soldering apparatus comprising:

a holder supporting a component with leads to be soldered;

a reservoir for molten solder;

a member assembly including an elongate plate provided in the reservoir and positioned at a surface of the molten solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder; and

means for lowering the solder surface away from said holder for effecting withdrawal of the component leads from the solder;

wherein said plate is electrically controlled such that it is movable relative to the solder surface.

Claims 30-36. (Cancelled)

5